

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A flip chip mounting substrate which comprises
an electronic circuit composed of a circuit line and plural mounting pads connected to both ends of the circuit line formed on one surface of a base sheet,
wherein the plural mounting pads ~~are faced~~face each other and are spaced a pad clearance gap apart, ~~and~~;
one or more semiconductor mounting paste guide paths are formed in the mounting pads;
a broad section for pressing out and spreading uniformly the semiconductor mounting paste for connecting to an IC chip is formed in a part of the pad clearance gap; and
a thin film layer is formed in a center section of the broad section.
2. (original): The flip chip mounting substrate as claimed in claim 1, wherein a width of the semiconductor mounting paste guide path is in the range from 50 to 600 μm .
3. and 4. (cancelled).